

Nanophotonics and Microcavities for Dense WDM Systems

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Report Documentation Page

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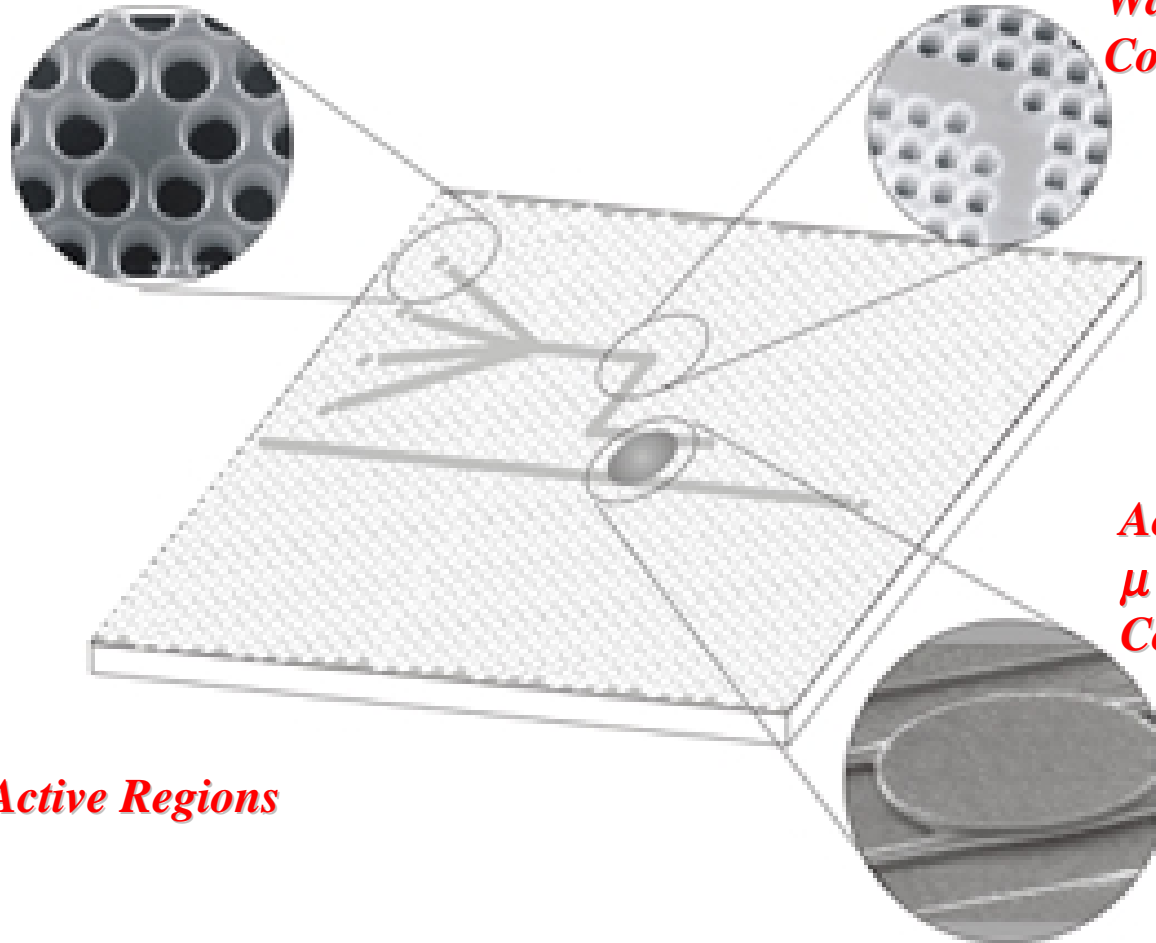
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Integrated Nanophotonic Technology

Photonic Crystal Defect Nanolasers

*Photonic Crystal
Waveguide
Components*



*Active and Passive
 μ resonator
Components*

QW and QD Active Regions

μ Disk and Photonic Crystal Devices for DWDM Systems

- **High Density Integrated Systems**
 - VLSI Photonic Integrated Circuits**
- **Compact, Low Power Components**
 - Millimeters \longrightarrow Microns**
- **Single or Multi-wavelength Resonant Components**
- **New Functionality in Active Components**

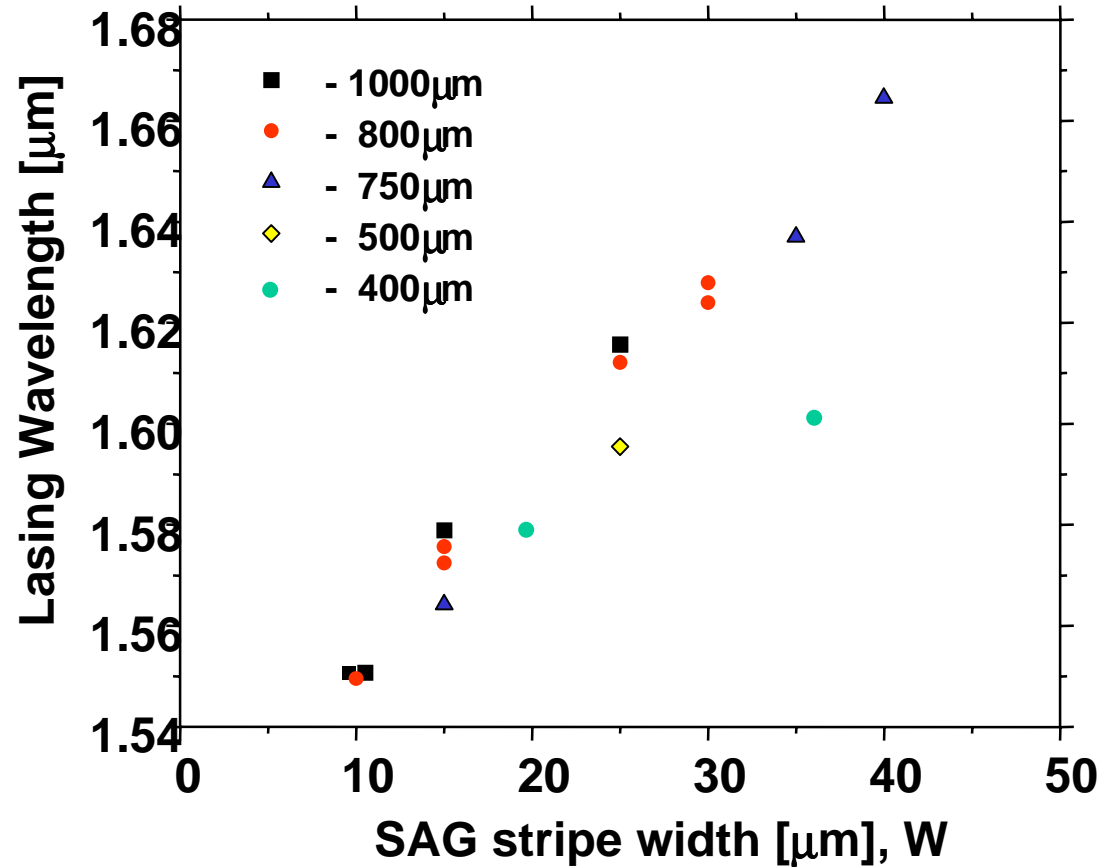
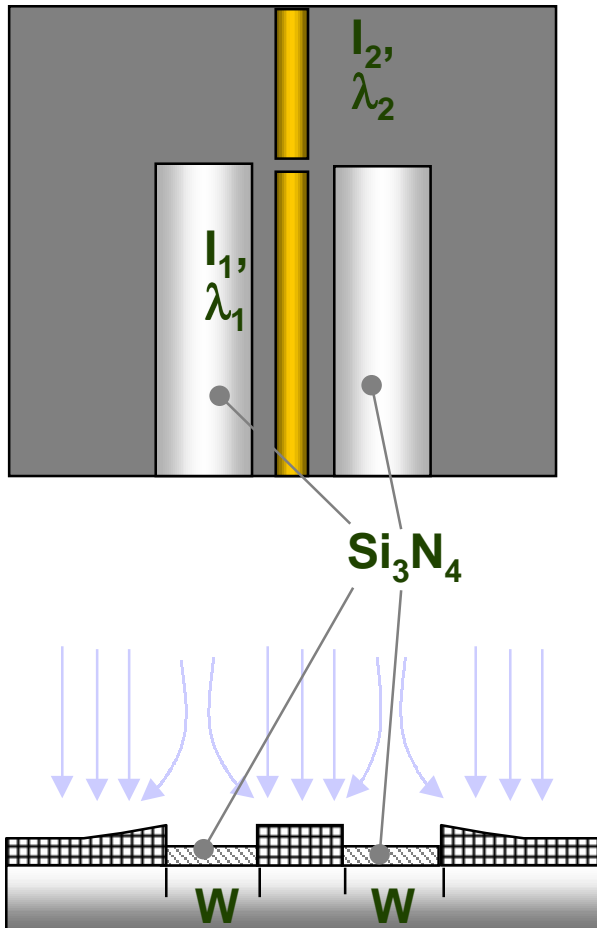
Integrable Nanophotonic Components

- *DWDM μ -Disk and Nanolasers and Arrays*
- *Tunable Lasers*
- *Dispersive, Superprism Propagation*
- *Low Voltage, High Bit Rate Modulators*
- *Wavelength Selective Switches*
- *Narrow Band Tunable Filters and Detectors*
- *Wavelength Selective Couplers and Splitters*
- *Chemical and Biological Sensor Elements*
- *Waveguide to Fiber Couplers*

Nanophotonic Technologies

- *High Q Resonators*
- ✓ *Heterogeneous Integration*
- ✓ *Electron Beam Lithography*
- ✓ *Highly Asymmetric Dry Etching*
- ✓ *Selective Area Epitaxy*
- ✓ *QW and QD Active Regions*

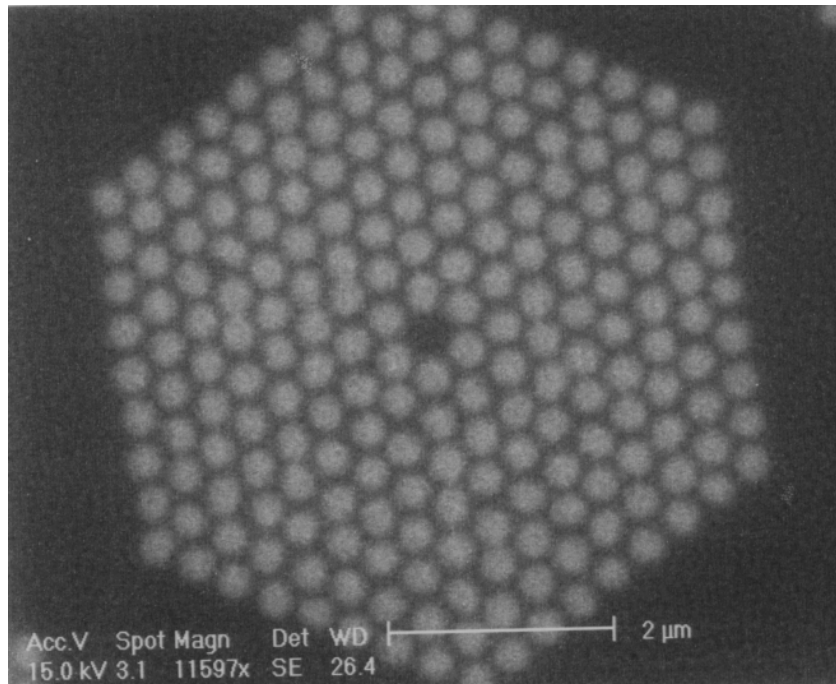
Selectively Grown Active Regions



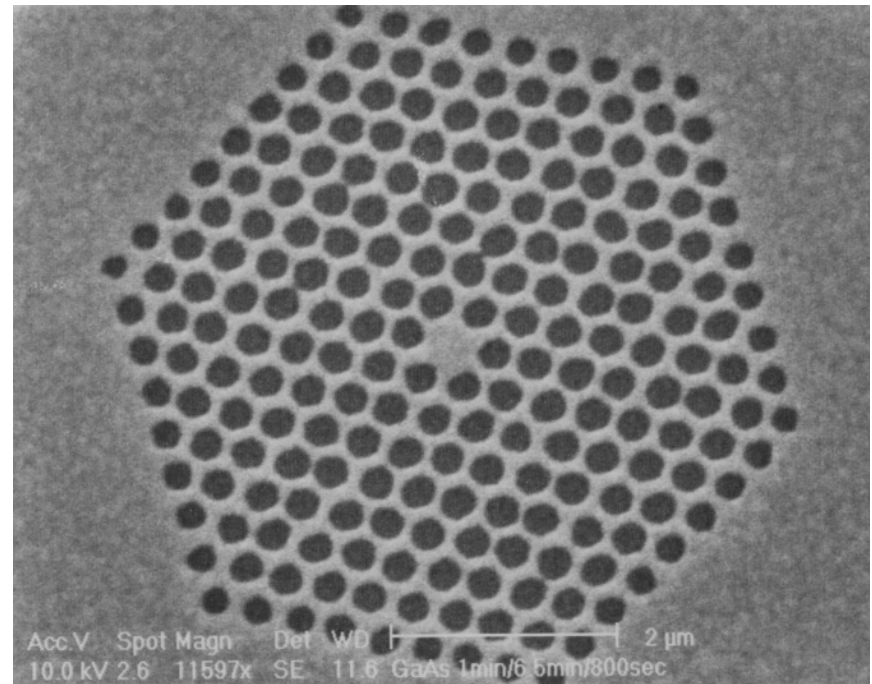
Resonant Cavity Structures

$r = 135 \text{ nm}$

$a = 400 \text{ nm}$

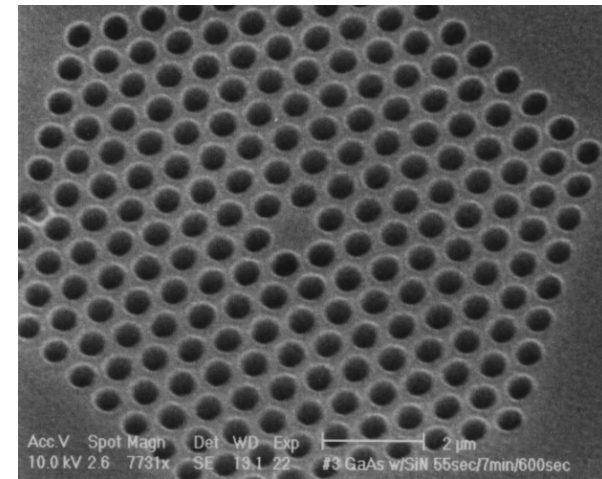
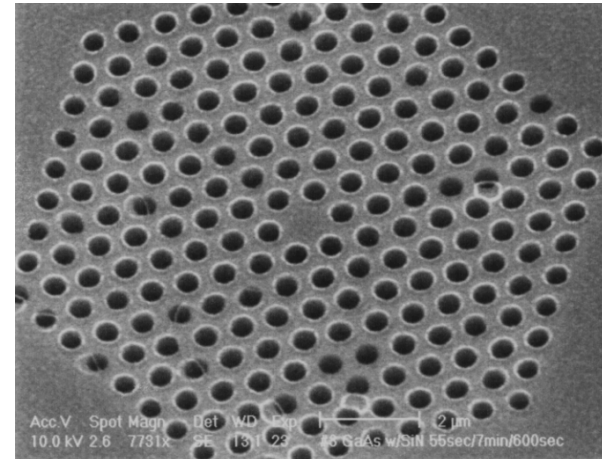
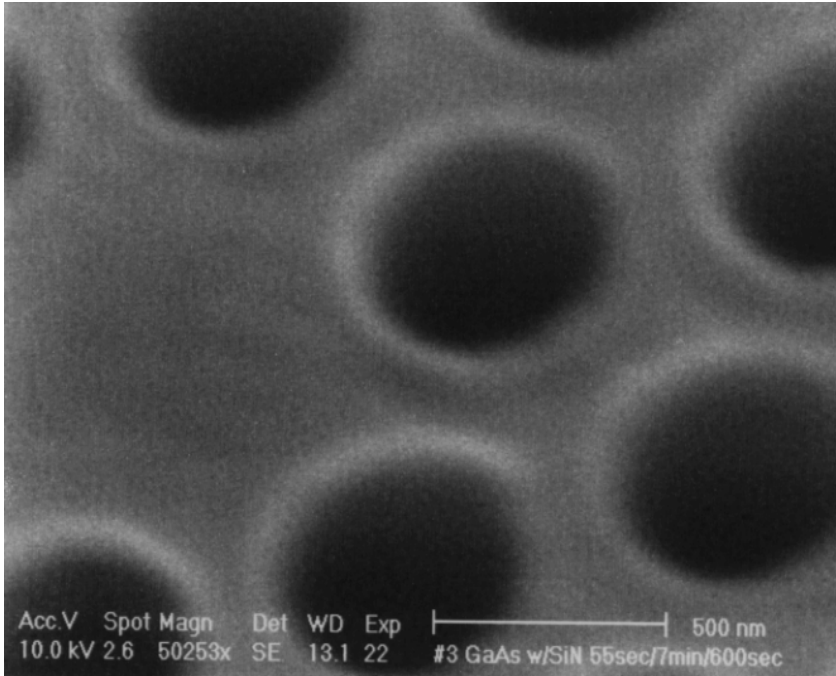


After Lithography

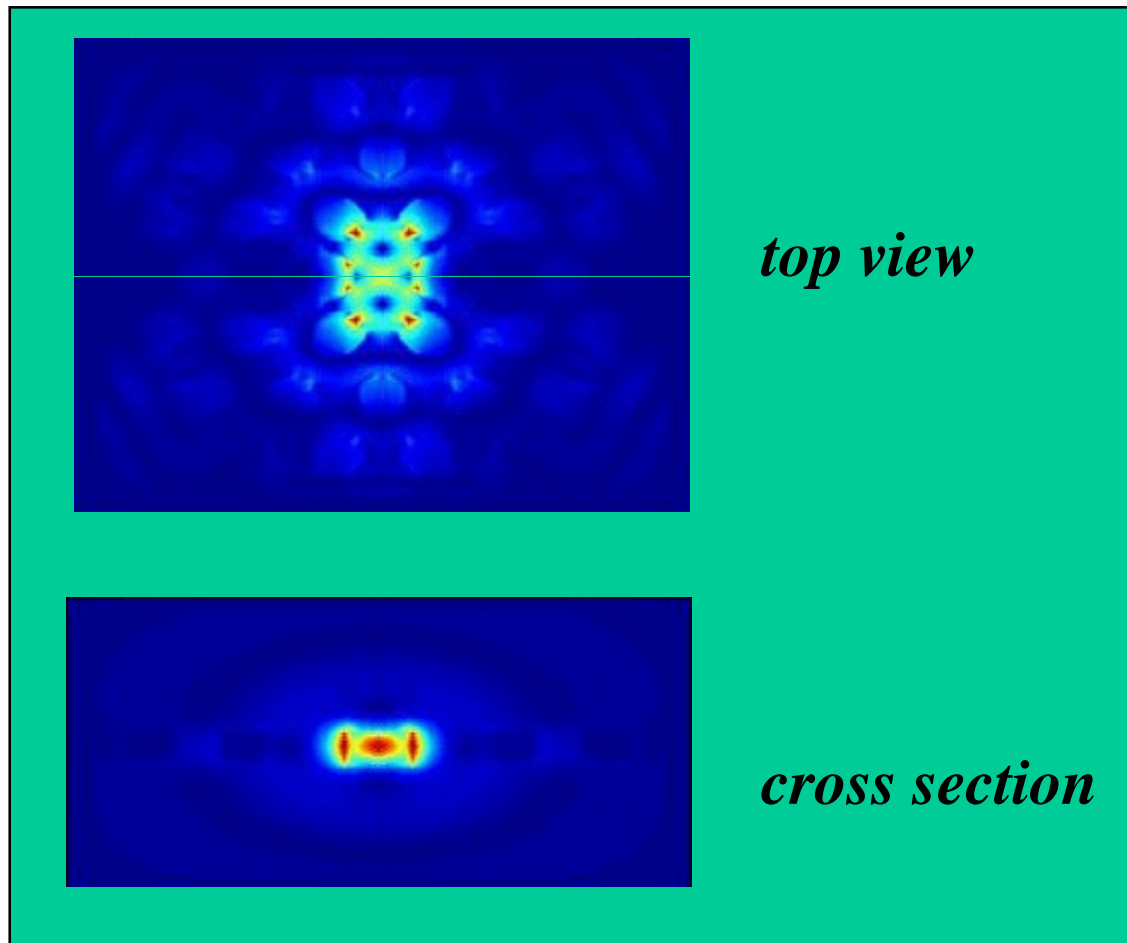


After RIE Etch

Top Views of GaAs PBGs after ECR etch

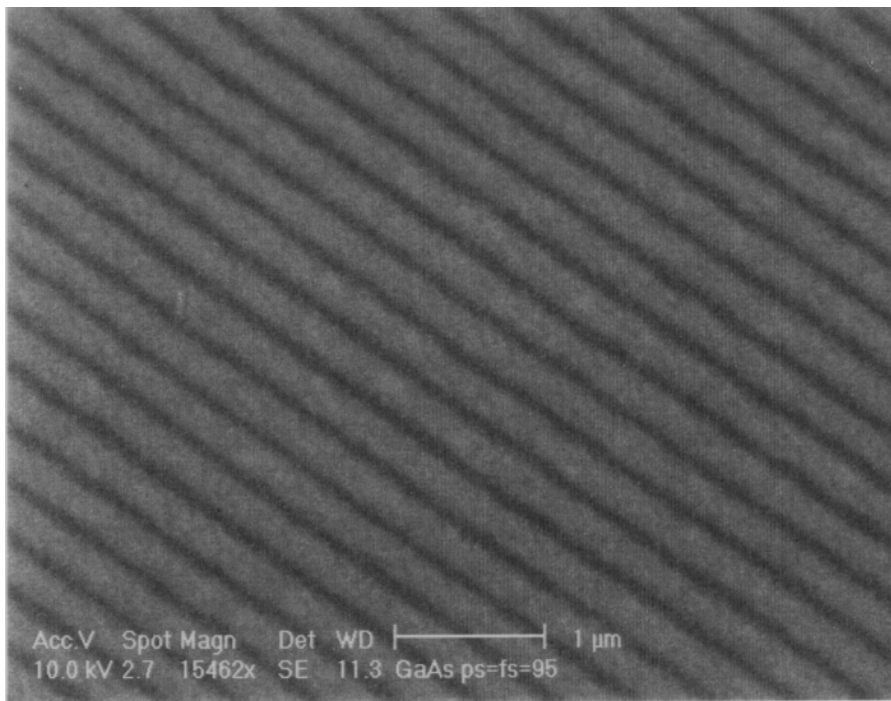


Magnitude of the Electric Field in the Defect Cavity

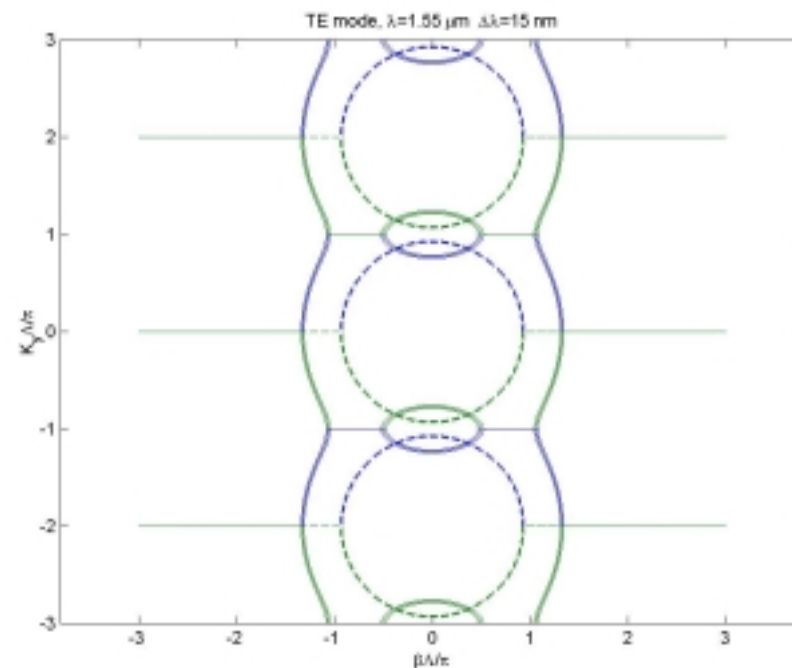


One-Dimensional Lattices

sample after lithography



dispersion surface



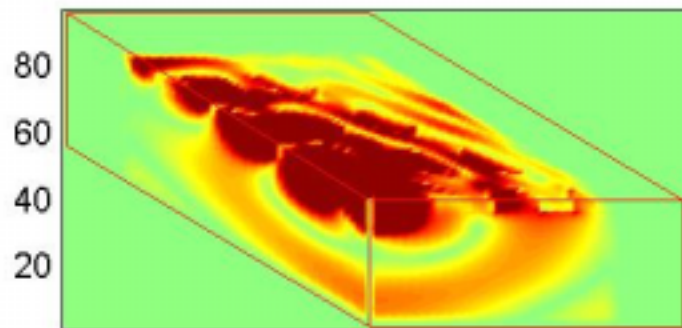
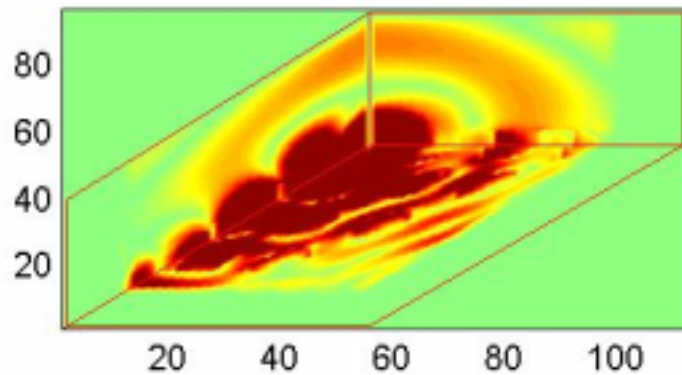
Superprism effect can be used for routing or multiplexing/demultiplexing

$$\vec{v}_g = \nabla_{\vec{k}} \omega(\mathbf{k})$$

Magnitude of the Electric Field in the Defect Cavity

symmetric cladding

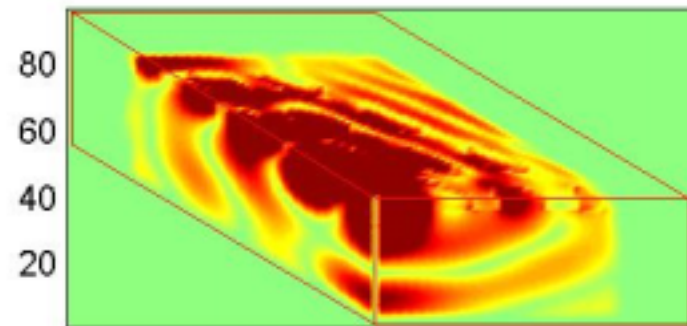
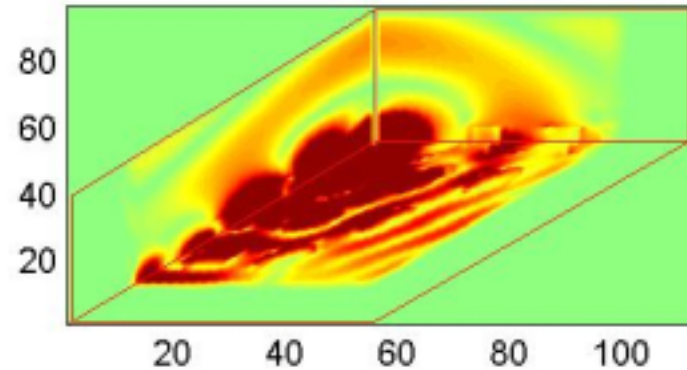
top



bottom

asymmetric cladding

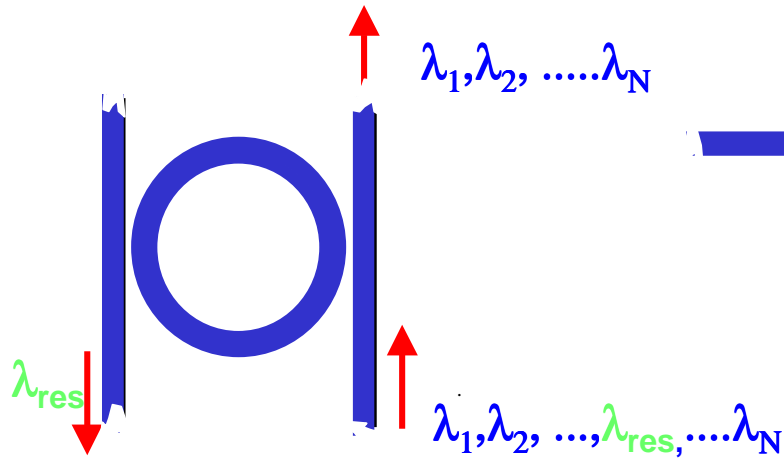
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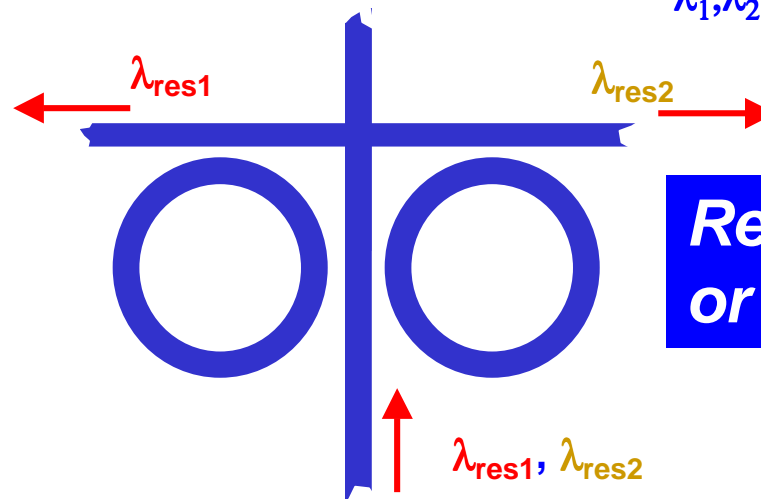
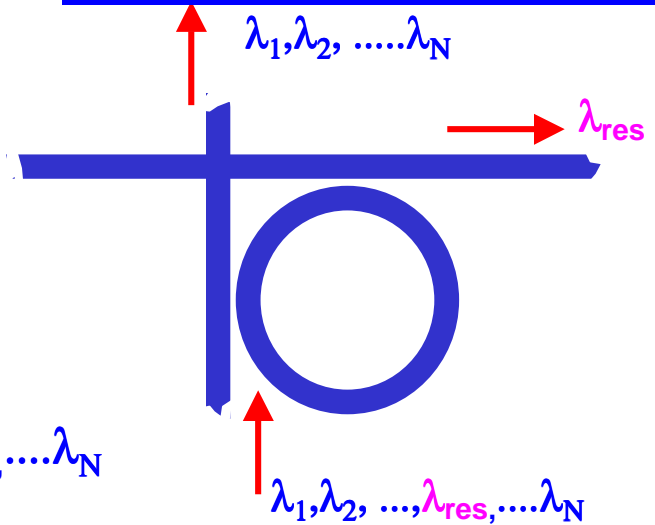
bottom

μ Resonator Structures

Resonant Filter / Switch

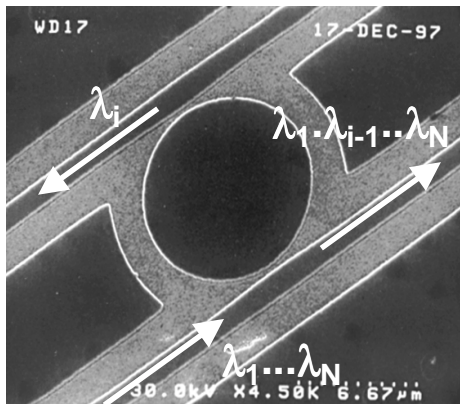


Resonant Y or Splitter



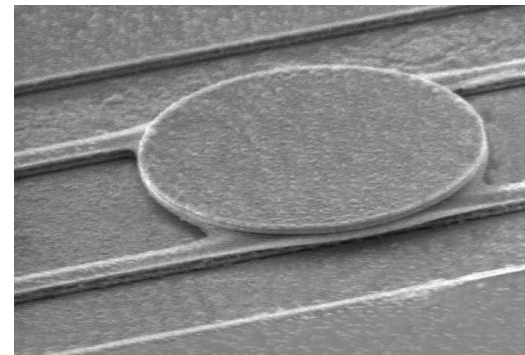
**Resonant T
or Splitter**

Vertical Coupler Fabricated by Heterogeneous Integration



OLD

NEW



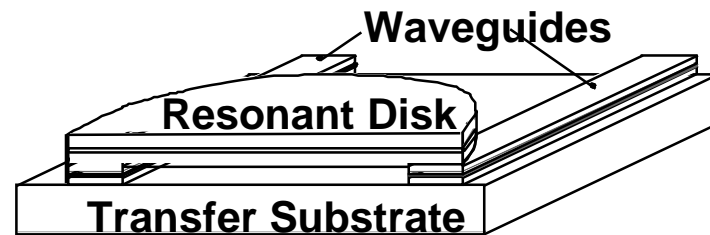
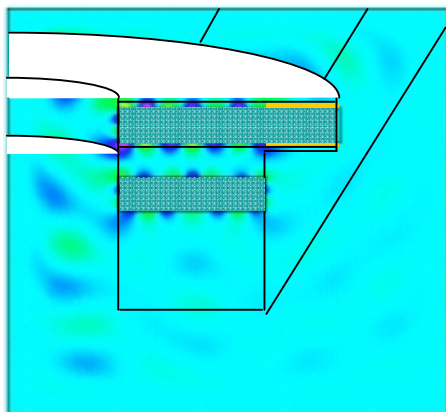
Laterally Coupled Disk

- Air Coupling
- Sub Micron Control

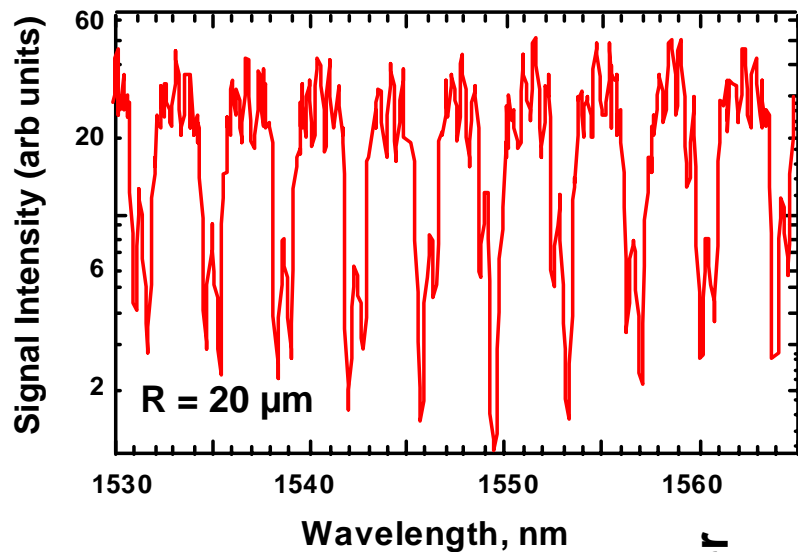
- Add-Drop Filters
- Resonant Detectors
- Integrated Lasers
- Resonant Modulators

Vertically Coupled Disk

- Epi Layer Coupling
- Control Coupling by Epilayer Thickness



μ Disk Resonant Components



← *Passive μ disk coupler*

*Active μ disk
tunable filter / switch* →

